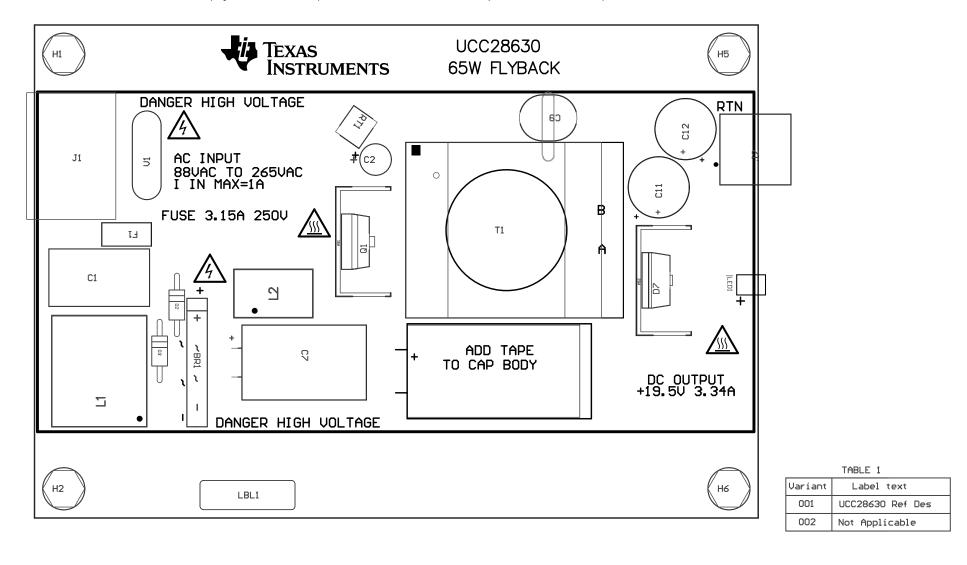
- ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9208	REV: E2	SUN REU	: Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 15/04/	·2014 12: 25: 27	1	TEXAS INSTRUMENTS

DNP DAD SAN (Lbs) PAL AC INPUT 88UAC TO 265UAC PAL IN MAX = 1MA NEUTRAL DANGER HIGH VOLTAGE RTN TUOU+ R16 S ΓINE (TPI **NBN**TK DC 0UTPUT +19,50 3,34A DANGER HIGH VOLTAGE **DWD9208 E2 GND** (TP3 **65W FLYBACK** DNP DNP UCC28630

BOARD #: PMP9208

GENERATED

REV: E2

12: 25: 27

IGNORE ->

: 15/04/2014

SUN REU: Not In VersionControl

TEXAS INSTRUMENTS

Bottom Overlay

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

Bottom Assembly Drawing

PCB VIEWED FROM BOTTOM SIDE

PLOT NAME =

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